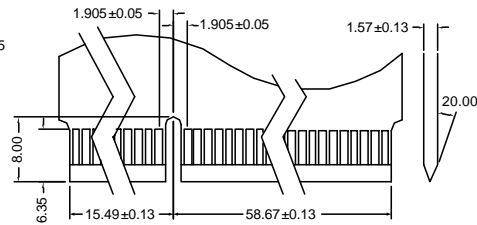
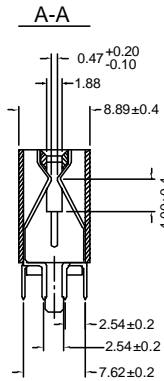


Recommended PCB Layout  
(Top View)



Daughter Card Requirements

**Material and Finish**

Body: Nylon 66  
High Temp Thermoplastic,  
UL94V-0 rated,  
25% glass filled

Contacts: Copper Alloy

Contact Plating: Gold Flash over  
Nickel on contact area,  
Tin/Lead over Nickel on  
termination end  
\*Other Plating Options Available  
Please Contact Factory for Details

**Mechanical Specifications**

- Insertion Force:  
8 oz. max.
- Separation Force:  
1 oz. min.
- Durability:  
100 cycles
- Steady State Humidity:  
90-95% RH at 40°C
- Vibration:  
10 G's, 10-500Hz, 2 Hrs.

**Electrical Specifications**

- Contact Current Rating:  
1 Amp
- Contact Resistance:  
30 Milliohms max.
- Insulation Resistance:  
5000 Megohms min. after  
exposure to humidity
- Dielectric Withstanding Voltage:  
500 Volts
- Operating Temperature:  
-50°C to +105°C



Tolerances
X.X ± 0.25
X.XX ± 0.15
Unless Stated Otherwise

REVISION	DATE	DESCRIPTION	DRAWN BY	DESIGNED BY	UNITS
D2	11/1/00	per ECD #00-075	C. Leiva		mm [in]
D3	12/15/00	per ECD #00-216	CHECKED BY	APPROVED BY	DATE
D4	10/05/01	per ECD #01-172			2/24/97

KHDS-112-G

High Density Edge Card Connector

0.05" pin spacing, plastic pegs

